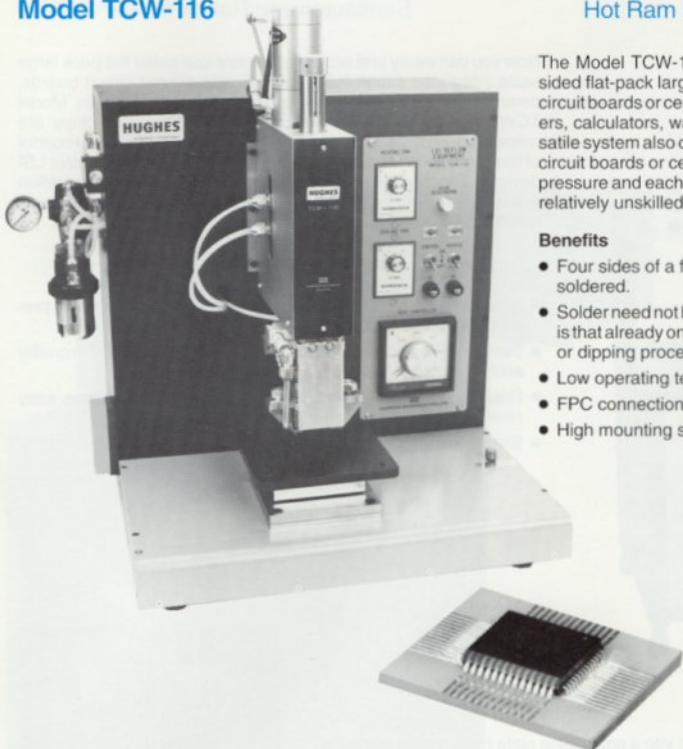


Model TCW-116

Hot Ram Reflow Solder system for 4-Sided LSI



The Model TCW-116 reflow solder system efficiently mounts four-sided flat-pack large scale integrated circuit (LSI) devices on printed circuit boards or ceramic substrates used in such products as computers, calculators, watches, cameras, and acoustic devices. This versatile system also connects flexible printed circuits (FPC) onto printed circuit boards or ceramic substrates. Precise control of temperature, pressure and each operation sequence is easily achieved, permitting relatively unskilled operators to solder with high reliability.

Benefits

- Four sides of a flat-pack LSI device can be simultaneously reflow soldered.
- Solder need not be supplied at each time of connection; solder used is that already on the circuit board or substrate from previous plating or dipping processes.
- Low operating temperature increases yield.
- FPC connections can be made on Polyimide surfaces.
- High mounting speed with high reliability enhances productivity.

**Operation**

The LSI device or FPC is positioned on the substrate or circuit board, which is then set on the work table or on a positioning fixture mounted to the work table. When the Model TCW-116 system's foot pedal is actuated, heater and holding plate are lowered into position. After the device is reflowed, the heater alone is raised automatically according to the preset heating time. The work is then cooled by forced air. At the end of the cooling cycle, the holding plate is raised automatically and joining is complete.

SPECIFICATIONS • Model TCW-116

Joining method	Reflow soldering
Input power	115 V or 230 V, 50 Hz or 60 Hz, 600 watts
	NOTE: Step-down transformer Model ST-100 included
Substrate size	4.80 in to 4.80 in (122 mm to 122 mm) max.
LSI size (dimension of connected portion)	0.40 in to 1.20 in (10 mm to 30 mm)
FPC size	4.00 in wide, (102 mm) max.
Heating temperature	100°C to 400°C
Heating time	1 to 10 seconds
Electrode force	6.60 to 66 lb (3 to 30 kg)
Throat depth	LSI: 6.20 in (157 mm) max. FPC: 6.80 in (173 mm)
Throat height (distance between work table and heater tip)	1.60 in (41 mm)
Stroke	1.20 in (30 mm) max.
Mounting speed (1 LSI)	8 to 10 seconds
Dimensions (H × W × D)	19 × 18.4 × 20.6 in (483 × 467 × 523 mm)
Weight	99 lb (45 kg)